

Method of forming a conductive pattern on dielectric substrates

Abstract:

To form a conductive pattern on dielectric substrates,
5 a method is proposed in which a) a substrate covered
with a metal film is coated with a protective layer
which is formed by treating the metal film with a
solution which contains at least one compound
containing nitrogen, b) the protective layer is
10 stripped away by UV radiation at least partially in the
regions which do not correspond to the conductive
pattern to be formed, in such a way that the metal film
is exposed, and c) the exposed metal film is then
removed by etching. By means of this method, extremely
15 fine conductive patterns can be manufactured in a
reproducible manner on dielectric substrates.

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